

- Low drain-source ON resistance: $R_{DS(ON)} = 0.54 \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 8.5 S$ (typ.)
- Low leakage current: $I_{DSS} = 100 \mu A$ (max) ($V_{DS} = 600 V$)
- Enhancement mode: $V_{th} = 2.0$ to $4.0 V$ ($V_{DS} = 10 V$, $I_D = 1 mA$)

Absolute Maximum Ratings ($T_a = 25^\circ C$)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	600	V
Drain-gate voltage ($R_{GS} = 20 k\Omega$)		V_{DGR}	600	V
Gate-source voltage		V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	10	A
	Pulse ($t = 1 ms$) (Note 1)	I_{DP}	40	
Drain power dissipation ($T_c = 25^\circ C$)		P_D	45	W
Single pulse avalanche energy (Note 2)		E_{AS}	363	mJ
Avalanche current		I_{AR}	10	A
Repetitive avalanche energy (Note 3)		E_{AR}	4.5	mJ
Channel temperature		T_{ch}	150	$^\circ C$
Storage temperature range		T_{stg}	-55 to 150	$^\circ C$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

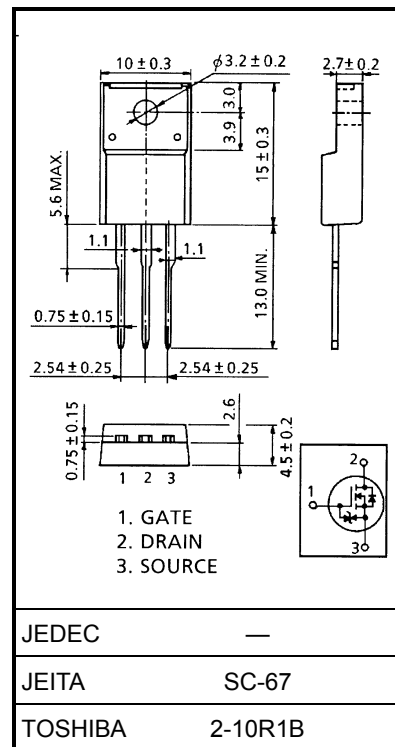
Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	2.78	$^\circ C/W$
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	62.5	$^\circ C/W$

Note 1: Ensure that the channel temperature does not exceed $150^\circ C$.

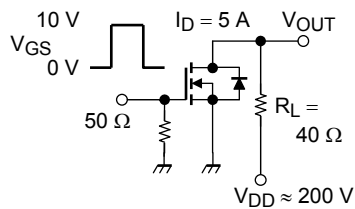
Note 2: $V_{DD} = 90 V$, $T_{ch} = 25^\circ C$ (initial), $L = 6.36 mH$, $I_{AR} = 10 A$, $R_G = 25 \Omega$

Unit: mm



Weight: 1.9 g (typ.)

Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	—	—	± 10	μA
Gate-source breakdown voltage		$V_{(BR)GSS}$	$I_G = \pm 10 \mu\text{A}, V_{DS} = 0 \text{ V}$	± 30	—	—	V
Drain cut-off current		I_{DSS}	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$	—	—	100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	600	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$	2.0	—	4.0	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	—	0.54	0.75	Ω
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10 \text{ V}, I_D = 5 \text{ A}$	2.4	8.5	—	S
Input capacitance		C_{iss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	—	1500	—	pF
Reverse transfer capacitance		C_{rss}		—	15	—	
Output capacitance		C_{oss}		—	180	—	
Switching time	Rise time	t_r	 <p>Duty $\leq 1\%$, $t_w = 10 \mu\text{s}$</p>	—	22	—	ns
	Turn-on time	t_{on}		—	50	—	
	Fall time	t_f		—	36	—	
	Turn-off time	t_{off}		—	180	—	
Total gate charge		Q_g	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	—	42	—	nC
Gate-source charge		Q_{gs}		—	23	—	
Gate-drain charge		Q_{gd}		—	19	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	10	A
Pulse drain reverse current (Note 1)	I_{DRP}	—	—	—	40	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	-1.7	V
Reverse recovery time	t_{rr}	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V},$	—	1300	—	ns
Reverse recovery charge	Q_{rr}	$dI_{DR}/dt = 100 \text{ A}/\mu\text{s}$	—	16	—	μC

Marking

